

PCN # 2276A

DATE: March 9, 2023

EXPECTED PCN SHIP DATE: March 9, 2023



Quality Assurance  
160 Rio Robles  
San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE  
 PRODUCT CHANGE NOTICE

ANALOG DEVICES HEREBY ISSUES NOTIFICATION OF CHANGE  
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

DESIGN     WAFER FAB     ASSEMBLY     TEST     ELEC/MECH SPECS

AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: - Transfer of the fabrication location for the final top copper metal layer for ADI commercial devices in TMA (Thick Metal Add-on) process. Current location at ADI/Beaverton/USA (ADBN)	CHANGE TO: -  New location at ADI/Limerick/Ireland (ADLK)
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JUSTIFICATION: -  
The location change to ADLK is necessary to ensure Manufacturing Efficiency.

1. The fab location of the wafer front-end process is unchanged.
2. There are no changes to materials, film thicknesses, or critical dimensions.
3. There are no datasheet changes for these products.
4. No Changes to Form/FIT/Function, or Reliability and Quality.

ADLK Qualification report is attached (ref. RQR43466A)

TRACEABILITY: Analog Device maintains full traceability by device marking, packaging labels and shipment documents.

Analog Devices's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

*Nasser Ali Chaouche*

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Analog Devices Company Representative    or    Nasser AliChaouche, PCN Coordinator  
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